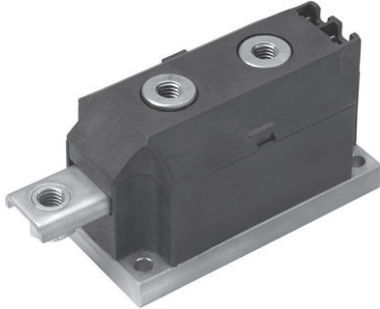


SCR/SCR and SCR/Diode (MAGN-A-PAK Power Modules), 230 A


MAGN-A-PAK
FEATURES

- High voltage
- Electrically isolated base plate
- 3500 V_{RMS} isolating voltage
- Industrial standard package
- Simplified mechanical designs, rapid assembly
- High surge capability
- Large creepage distances
- UL approved file E78996
- Compliant to RoHS directive 2002/95/EC
- Designed and qualified for industrial level


**RoHS
COMPLIANT**
PRODUCT SUMMARY

$I_{T(AV)}$	230 A
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DESCRIPTION

This new VSK series of MAGN-A-PAK modules uses high voltage power thyristor/thyristor and thyristor/diode in seven basic configurations. The semiconductors are electrically isolated from the metal base, allowing common heatsinks and compact assemblies to be built. They can be interconnected to form single phase or three phase bridges or as AC-switches when modules are connected in anti-parallel mode. These modules are intended for general purpose applications such as battery chargers, welders, motor drives, UPS, etc.

MAJOR RATINGS AND CHARACTERISTICS

SYMBOL	CHARACTERISTICS	VALUES	UNITS
$I_{T(AV)}$	85 °C	230	A
$I_{T(RMS)}$		510	
I_{TSM}	50 Hz	7500	
	60 Hz	7850	
I^2t	50 Hz	280	kA ² s
	60 Hz	260	
$I^2\sqrt{t}$		280	kA ² √s
V_{DRM}/V_{RRM}		Up to 2000	V
T_J	Range	- 40 to 130	°C

ELECTRICAL SPECIFICATIONS
VOLTAGE RATINGS

TYPE NUMBER	VOLTAGE CODE	V_{RRM}/V_{DRM} , MAXIMUM REPETITIVE PEAK REVERSE AND OFF-STATE BLOCKING VOLTAGE V	V_{RSM} , MAXIMUM NON-REPETITIVE PEAK REVERSE VOLTAGE V	I_{RRM}/I_{DRM} AT 130 °C MAXIMUM mA
VSK.230-	08	800	900	50
	12	1200	1300	
	16	1600	1700	
	18	1800	1900	
	20	2000	2100	

ON-STATE CONDUCTION					
PARAMETER	SYMBOL	TEST CONDITIONS		VALUES	UNITS
Maximum average on-state current at case temperature	$I_{T(AV)}$	180° conduction, half sine wave		230	A
				85	°C
Maximum RMS on-state current	$I_{T(RMS)}$	As AC switch		510	
Maximum peak, one-cycle on-state non-repetitive, surge current	I_{TSM}	t = 10 ms	No voltage reapplied	Sinusoidal half wave, initial $T_J = T_J$ maximum	A
		t = 8.3 ms			
		t = 10 ms	100 % V_{RRM} reapplied		
		t = 8.3 ms			
Maximum I^2t for fusing	I^2t	t = 10 ms	No voltage reapplied		kA ² s
		t = 8.3 ms			
		t = 10 ms	100 % V_{RRM} reapplied		
		t = 8.3 ms			
Maximum $I^2\sqrt{t}$ for fusing	$I^2\sqrt{t}$	t = 0.1 ms to 10 ms, no voltage reapplied		2800	kA ² √s
Low level value or threshold voltage	$V_{T(TO)1}$	$(16.7\% \times \pi \times I_{T(AV)} < I < \pi \times I_{T(AV)})$, $T_J = T_J$ maximum		1.03	V
High level value of threshold voltage	$V_{T(TO)2}$	$(I > \pi \times I_{T(AV)} < I < \pi \times I_{T(AV)})$, $T_J = T_J$ maximum		1.07	
Low level value on-state slope resistance	r_{t1}	$(16.7\% \times \pi \times I_{T(AV)} < I < \pi \times I_{T(AV)})$, $T_J = T_J$ maximum		0.77	mΩ
High level value on-state slope resistance	r_{t2}	$(I > \pi \times I_{T(AV)} < I < \pi \times I_{T(AV)})$, $T_J = T_J$ maximum		0.73	
Maximum on-state voltage drop	V_{TM}	$I_{TM} = \pi \times I_{T(AV)}$, $T_J = T_J$ maximum, 180° conduction, average power = $V_{T(TO)} \times I_{T(AV)} + r_f \times (I_{T(RMS)})^2$		1.59	V
Maximum holding current	I_H	Anode supply = 12 V, initial $I_T = 30$ A, $T_J = 25$ °C		500	mA
Maximum latching current	I_L	Anode supply = 12 V, resistive load = 1 Ω, gate pulse: 10 V, 100 μs, $T_J = 25$ °C		1000	

SWITCHING					
PARAMETER	SYMBOL	TEST CONDITIONS		VALUES	UNITS
Typical delay time	t_d	$T_J = 25$ °C, gate current = 1 A $di_g/dt = 1$ A/μs		1.0	μs
Typical rise time	t_r	$V_d = 0.67\% V_{DRM}$		2.0	
Typical turn-off time	t_q	$I_{TM} = 300$ A; $di/dt = 15$ A/μs; $T_J = T_J$ maximum; $V_R = 50$ V; $dV/dt = 20$ V/μs; gate 0 V, 100 Ω		50 to 150	

BLOCKING					
PARAMETER	SYMBOL	TEST CONDITIONS		VALUES	UNITS
Maximum peak reverse and off-state leakage current	I_{RRM} , I_{DRM}	$T_J = T_J$ maximum		50	mA
RMS insulation voltage	V_{INS}	50 Hz, circuit to base, all terminals shorted, 25 °C, 1 s		3000	V
Critical rate of rise of off-state voltage	dV/dt	$T_J = T_J$ maximum, exponential to 67 % rated V_{DRM}		1000	V/μs



TRIGGERING					
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS	
Maximum peak gate power	P_{GM}	$t_p \leq 5$ ms, $T_J = T_J$ maximum	10.0	W	
Maximum average gate power	$P_{G(AV)}$	$f = 50$ Hz, $T_J = T_J$ maximum	2.0		
Maximum peak gate current	$+ I_{GM}$	$t_p \leq 5$ ms, $T_J = T_J$ maximum	3.0	A	
Maximum peak negative gate voltage	$- V_{GT}$	$t_p \leq 5$ ms, $T_J = T_J$ maximum	5.0	V	
Maximum required DC gate voltage to trigger	V_{GT}	$T_J = -40$ °C	Anode supply = 12 V, resistive load; $R_a = 1$ Ω		4.0
		$T_J = 25$ °C			3.0
		$T_J = T_J$ maximum			2.0
Maximum required DC gate current to trigger	I_{GT}	$T_J = -40$ °C	Anode supply = 12 V, resistive load; $R_a = 1$ Ω	350	
		$T_J = 25$ °C		200	
		$T_J = T_J$ maximum		100	
Maximum gate voltage that will not trigger	V_{GD}	$T_J = T_J$ maximum, rated V_{DRM} applied	0.25	V	
Maximum gate current that will not trigger	I_{GD}	$T_J = T_J$ maximum, rated V_{DRM} applied	10.0	mA	
Maximum rate of rise of turned-on current	di/dt	$T_J = T_J$ maximum, $I_{TM} = 400$ A, rated V_{DRM} applied	500	A/ μ s	

THERMAL AND MECHANICAL SPECIFICATIONS				
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Junction operating temperature range	T_J		- 40 to 130	°C
Storage temperature range	T_{Stg}		- 40 to 150	
Maximum thermal resistance, junction to case per junction	R_{thJC}	DC operation	0.125	K/W
Typical thermal resistance, case to heatsink per module	R_{thCS}	Mounting surface flat, smooth and greased	0.02	
Mounting torque ± 10 %	MAP to heatsink busbar to MAP	A mounting compound is recommended and the torque should be rechecked after a period of about 3 h to allow for the spread of the compound.	4 to 6	Nm
Approximate weight				
			17.8	oz.
Case style			MAGN-A-PAK	

ΔR CONDUCTION PER JUNCTION											
DEVICES	SINUSOIDAL CONDUCTION AT T_J MAXIMUM					RECTANGULAR CONDUCTION AT T_J MAXIMUM					UNITS
	180°	120°	90°	60°	30°	180°	120°	90°	60°	30°	
VSK.230-	0.009	0.010	0.010	0.020	0.032	0.007	0.011	0.015	0.020	0.033	K/W

Note

- Table shows the increment of thermal resistance R_{thJC} when devices operate at different conduction angles than DC

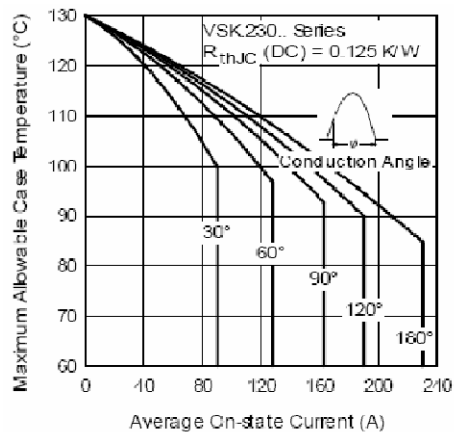


Fig. 1 - Current Ratings Characteristics

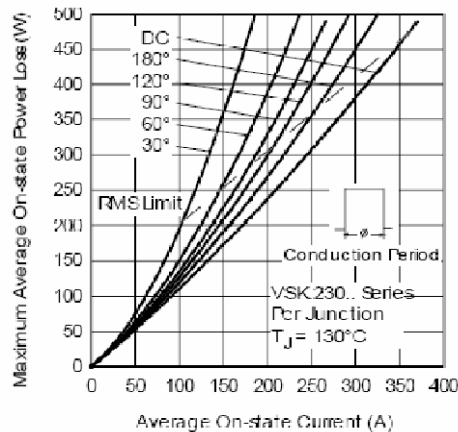


Fig. 4 - On-State Power Loss Characteristics

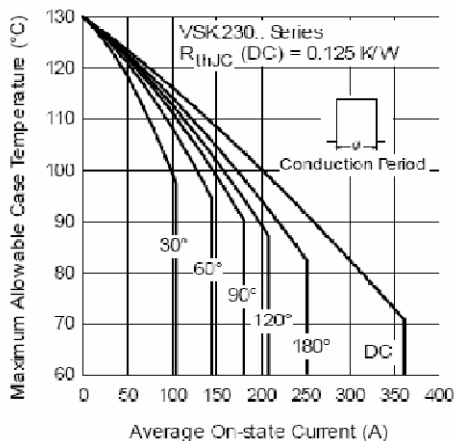


Fig. 2 - Current Ratings Characteristics

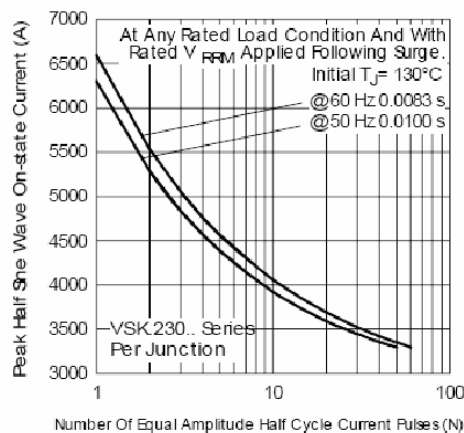


Fig. 5 - Maximum Non-Repetitive Surge Current

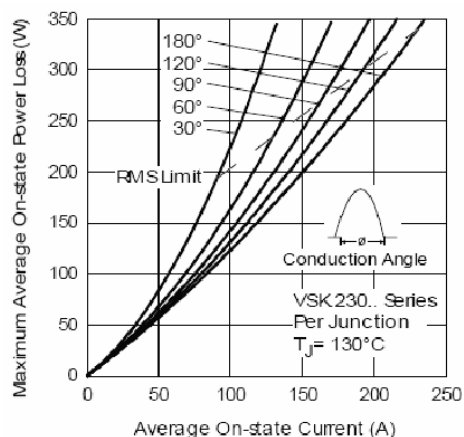


Fig. 3 - On-State Power Loss Characteristics

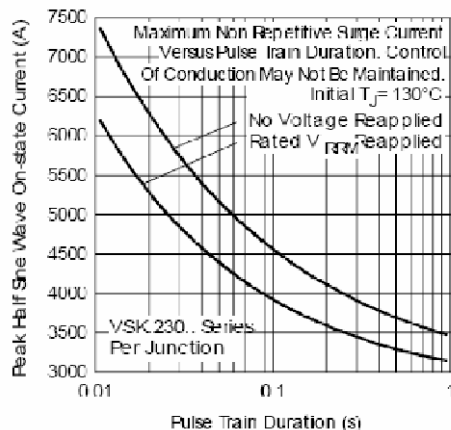


Fig. 6 - Maximum Non-Repetitive Surge Current



SCR/SCR and SCR/Diode
(MAGN-A-PAK Power Modules), 230 A

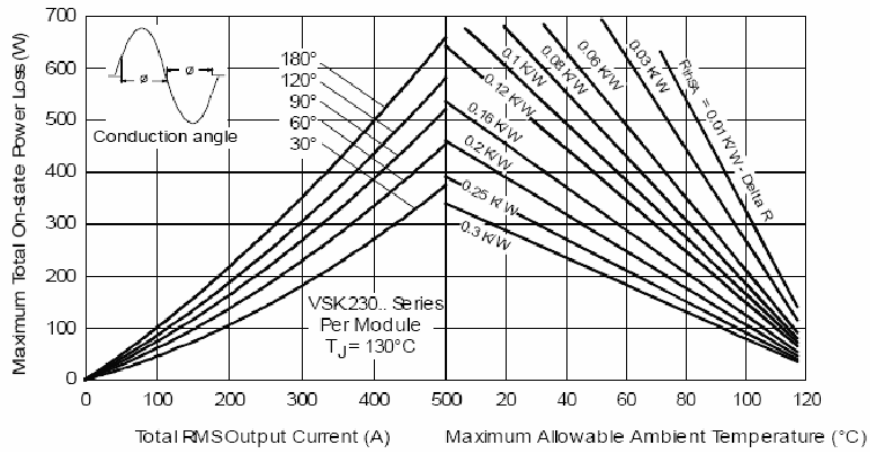


Fig. 7 - On-State Power Loss Characteristics

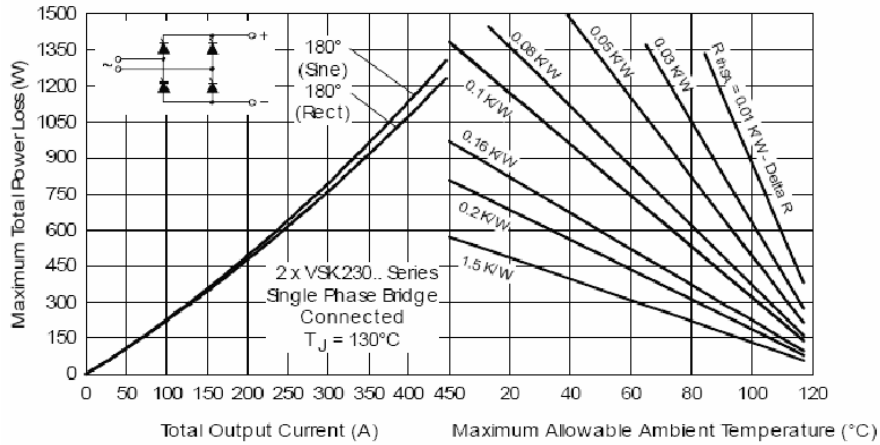


Fig. 8 - On-State Power Loss Characteristics

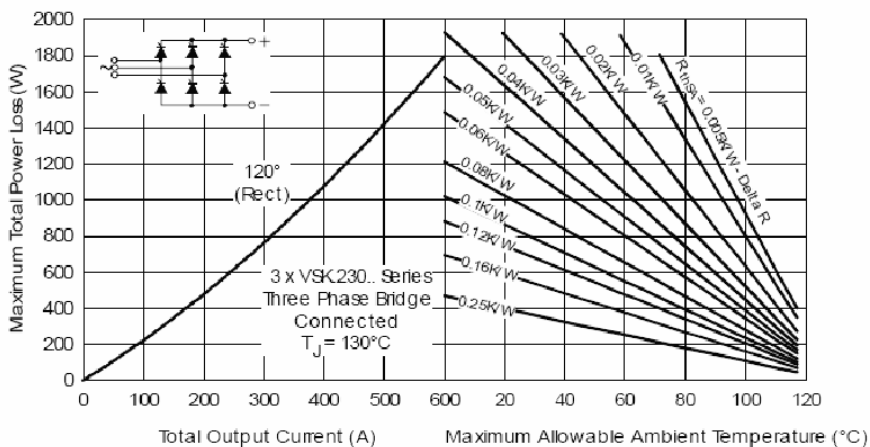


Fig. 9 - On-State Power Loss Characteristics

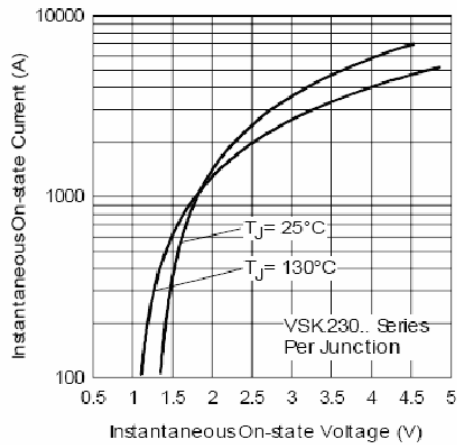


Fig. 10 - On-State Voltage Drop Characteristics

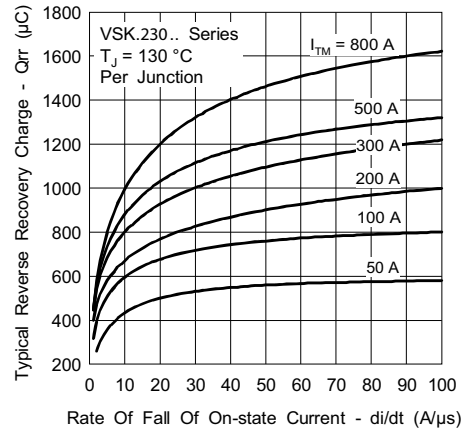


Fig. 11 - Reverse Recovery Charge Characteristics

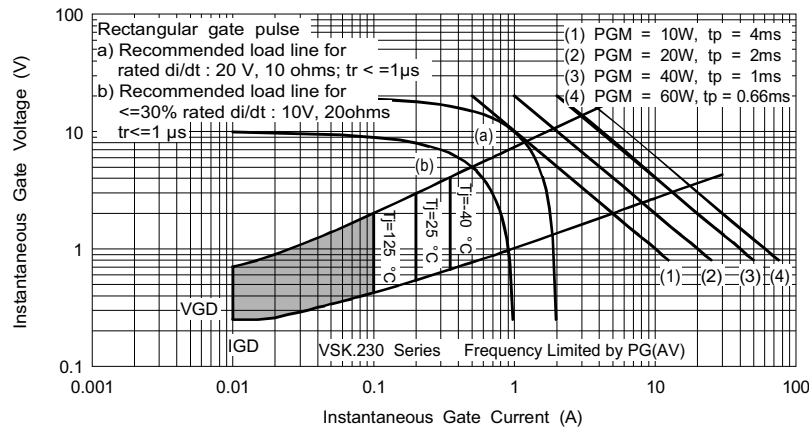


Fig. 12 - Gate Characteristics

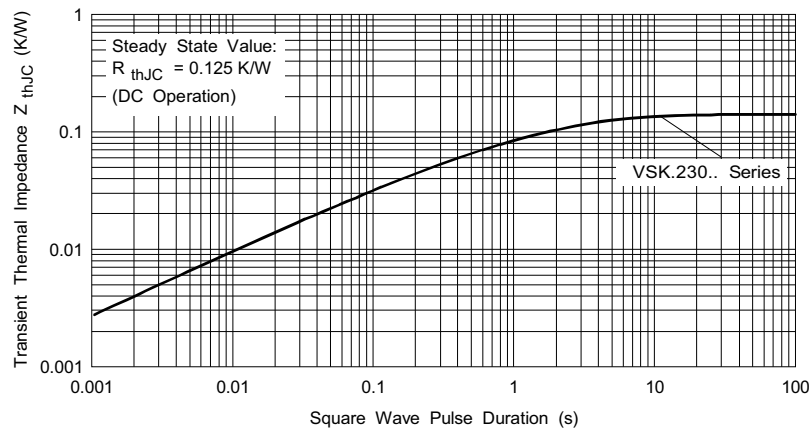


Fig. 13 - Thermal Impedance Z_{thJC} Characteristics

ORDERING INFORMATION TABLE

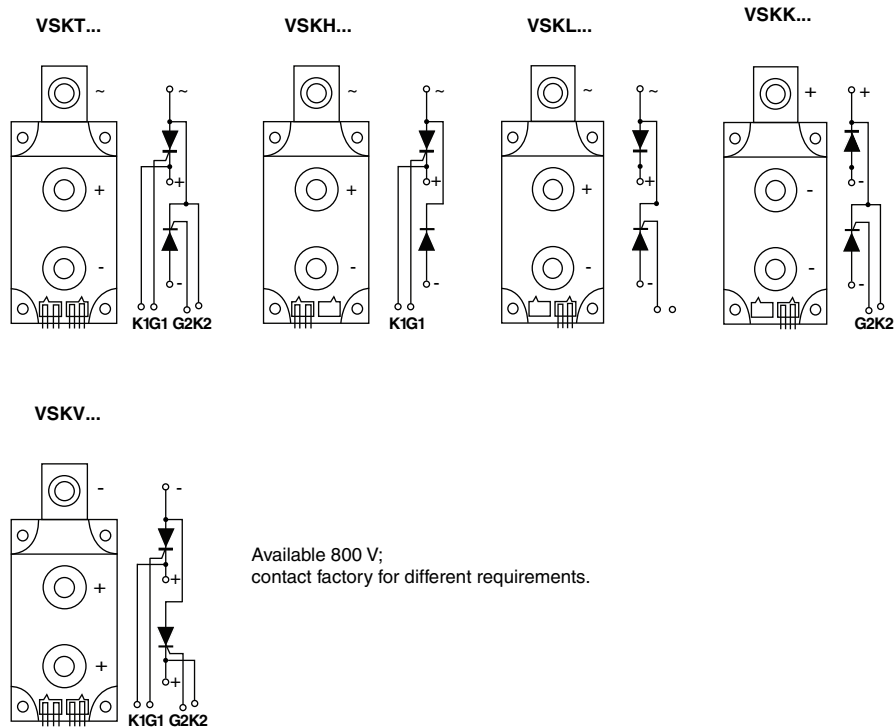
Device code	VSK	T	230	-	20	PbF
	①	②	③		④	⑤

- 1** - Module type
- 2** - Circuit configuration (see dimensions - link at the end of datasheet)
- 3** - Current rating
- 4** - Voltage code x 100 = V_{RRM} (see Voltage Ratings table)
- 5** -
 - None = Standard production
 - PbF = Lead (Pb)-free

Note

- To order the optional hardware go to www.vishay.com/doc?95172

CIRCUIT CONFIGURATION



LINKS TO RELATED DOCUMENTS

Dimensions	www.vishay.com/doc?95086
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